

Thermal Silicone Pad Series

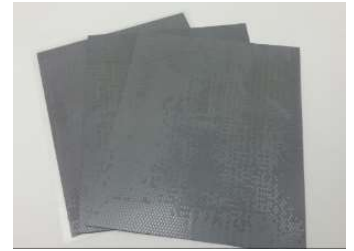
Products : TMT-180-B

TMT-180 Series

are used to fill the gaps between thermal transfer surfaces, such as between microprocessors and heat-sinks, in order to increase thermal transfer efficiency.

KEY FEATURES

- ▶ Elimination of air gaps to reduce thermal resistance
- ▶ High conformability to reduce interfacial resistance
- ▶ Low-stress vibration dampening
- ▶ Compatible with automated dispensing equipment



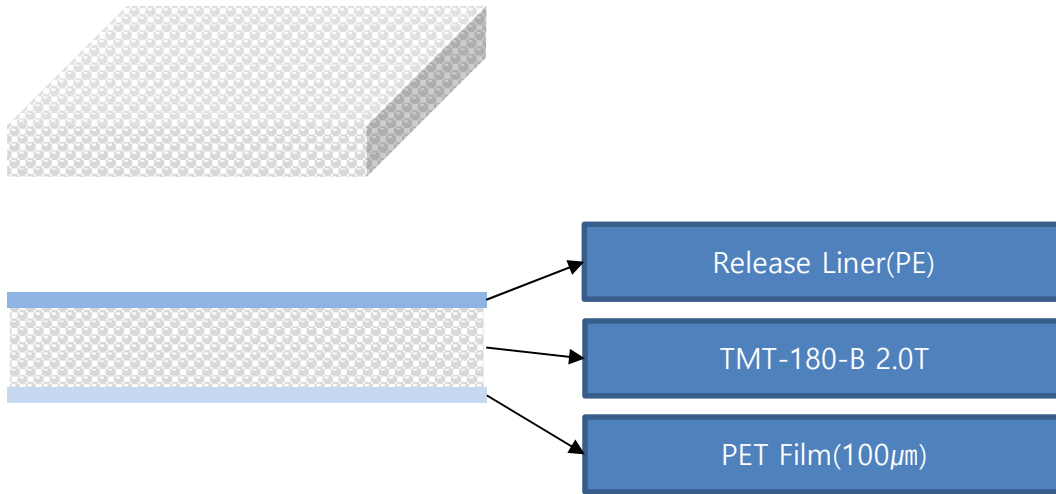
Product Photo

Typical Property	unit	TMT-180 Series	Test Method
Material	-	Silicone RTV and Ceramic fillers	
Color	-	Black	Visual
Thickness	mm	1.0 ~ 6.0	ASTM D374
Thermal Conductivity	W/m·k	1.5	ASTM D5470
Hardness	Shore 00	60 ± 10	ASTM D2240
Density	g/cm ³	1.8 ± 0.1	
Dielectric Strength	KV/mm	↑ 10	ASTM D149
Volume Resistivity	Ω•cm	10 ¹³	ASTM D257
Flammability	UL94	V-0	E257359
Temperature Range	°C	-40 ~ 200	-

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Structure



Die-Cutting